

**Reverse Voltage - 50 to 1000 V**

**Forward Current - 1 A**

## FEATURES

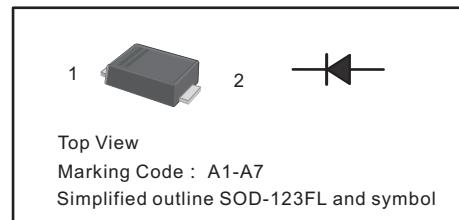
- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives

## MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 15mg / 0.00053oz

## PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



## Maximum Ratings and Electrical characteristics

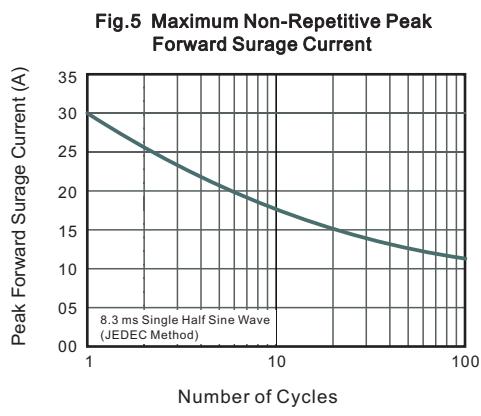
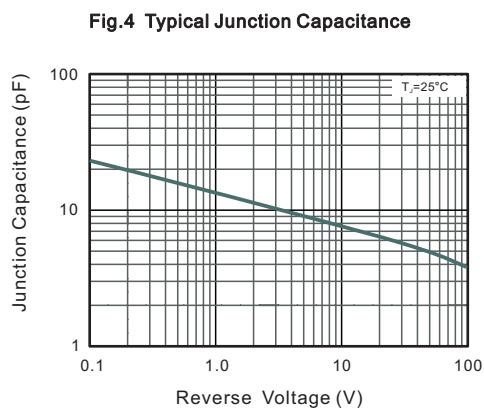
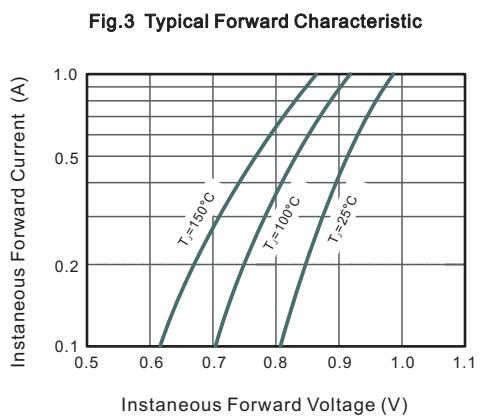
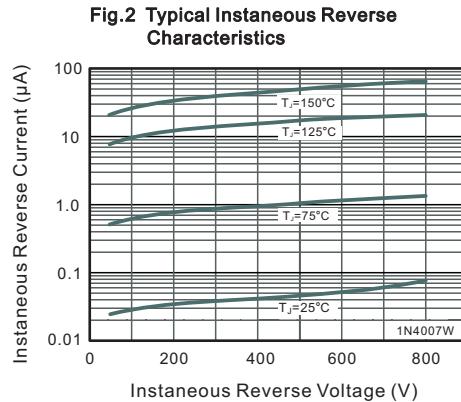
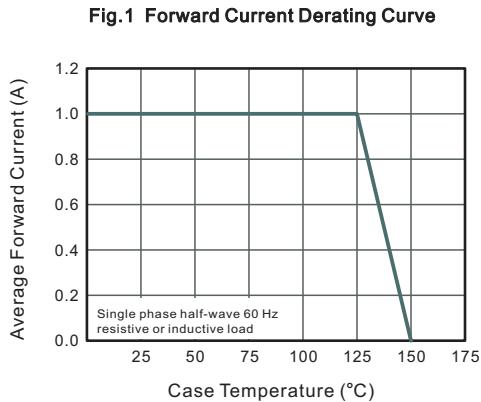
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	A 1	A 2	A 3	A 4	A 5	A 6	A 7	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 125^\circ\text{C}$	$I_{F(AV)}$	1						A	
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	30						A	
Maximum Instantaneous Forward Voltage at 1 A	$V_F$	1.1						V	
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125^\circ\text{C}$	$I_R$	5 50						$\mu\text{A}$	
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	11						pF	
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	90						$^\circ\text{C/W}$	
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ\text{C}$	

( 1 ) Measured at 1 MHz and applied reverse voltage of 4 V D.C

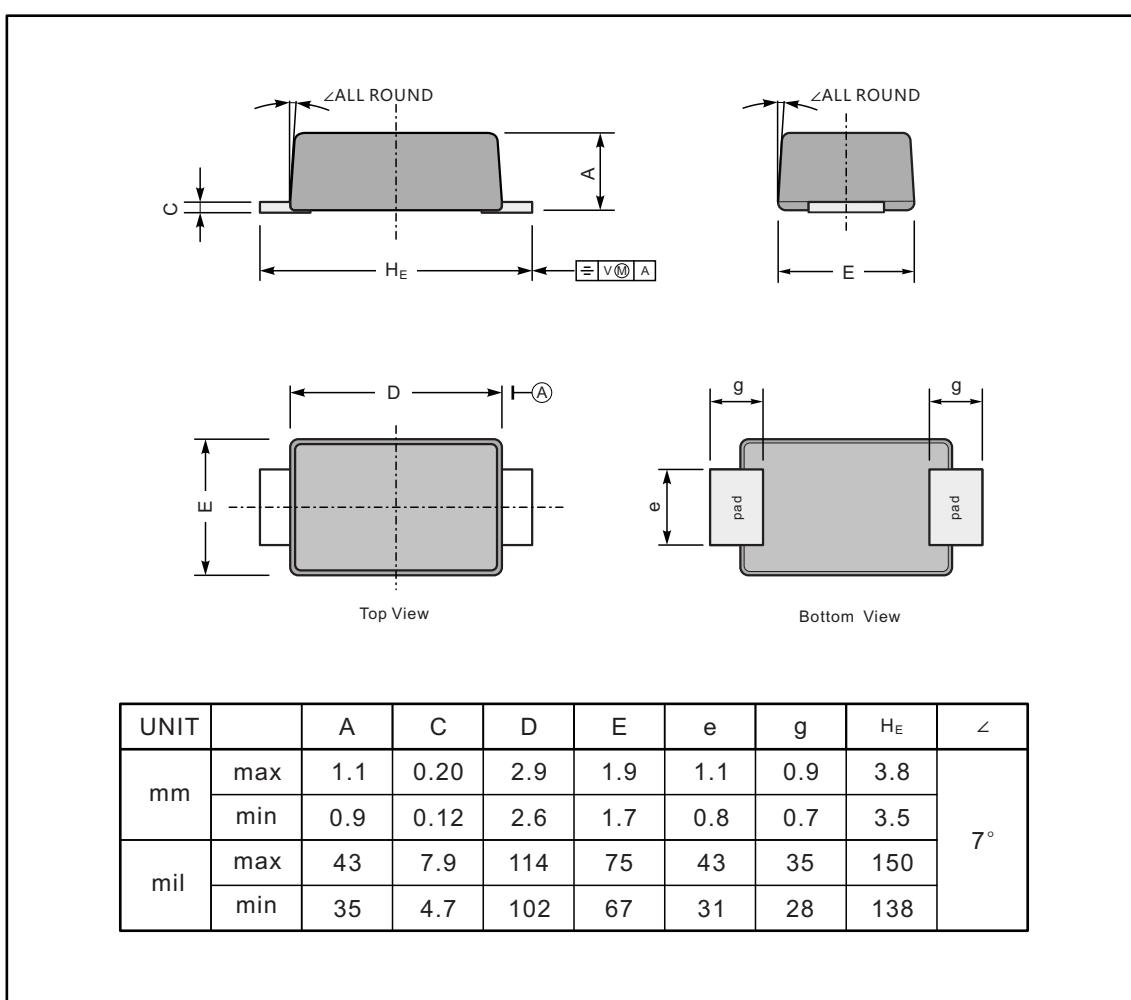
( 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



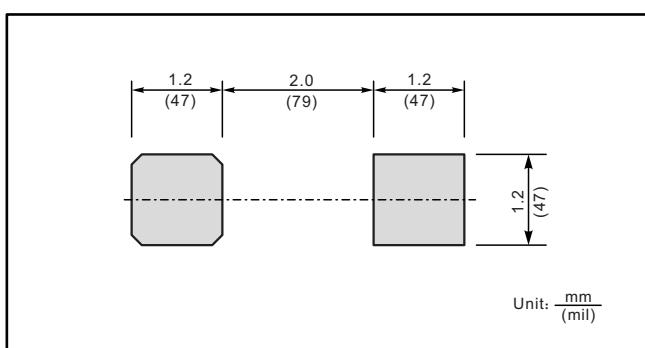
## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123FL



The recommended mounting pad size



Marking

Type number	Marking code
A1	A1
A2	A2
A3	A3
A4	A4
A5	A5
A6	A6
A7	A7